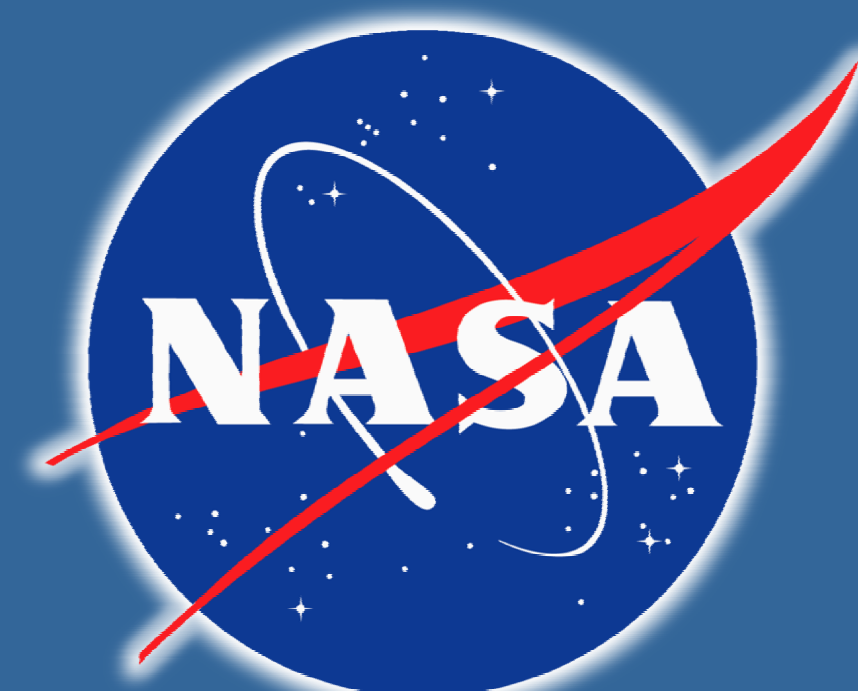




# Prognostics for Electronics

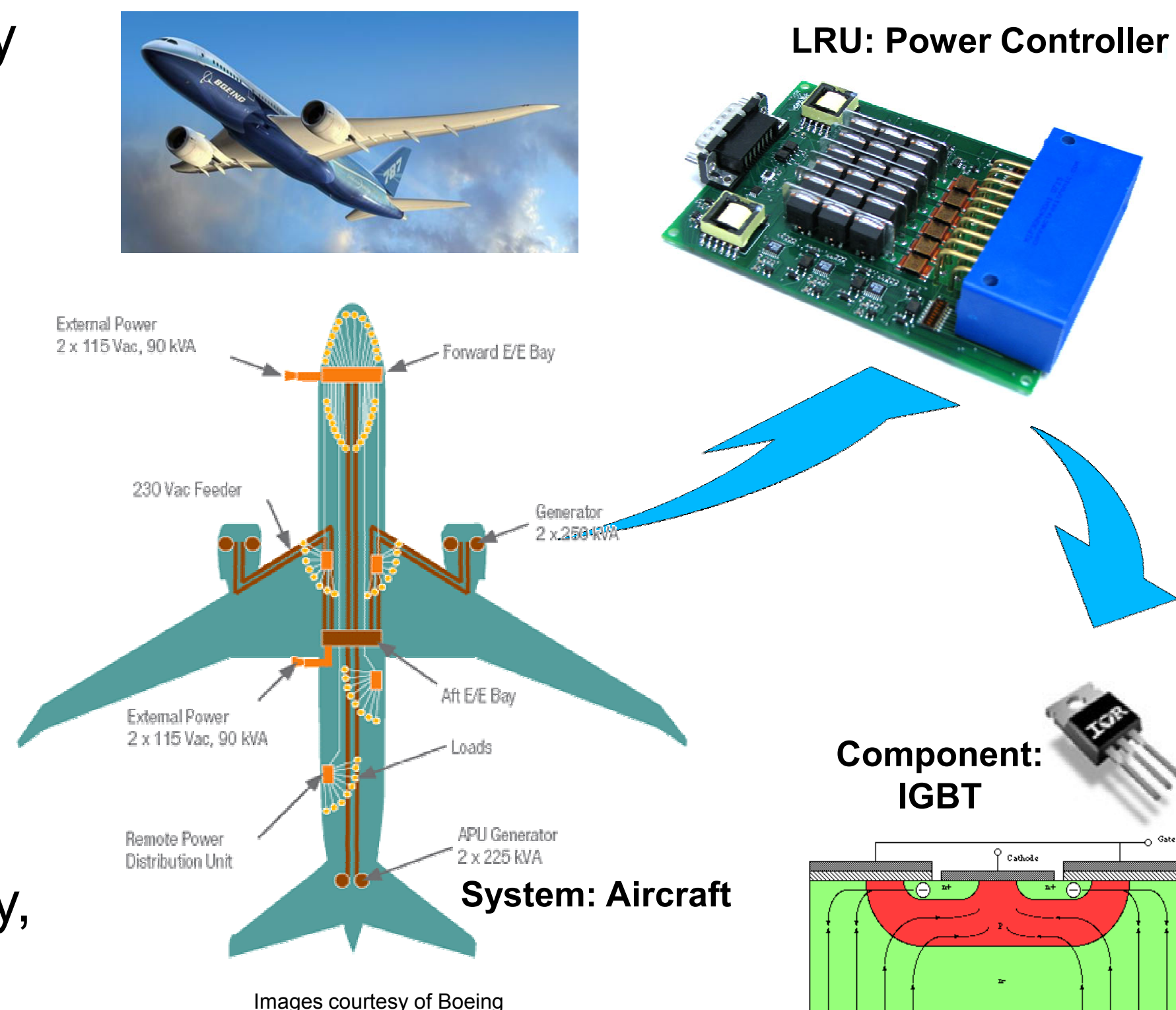
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## Overview

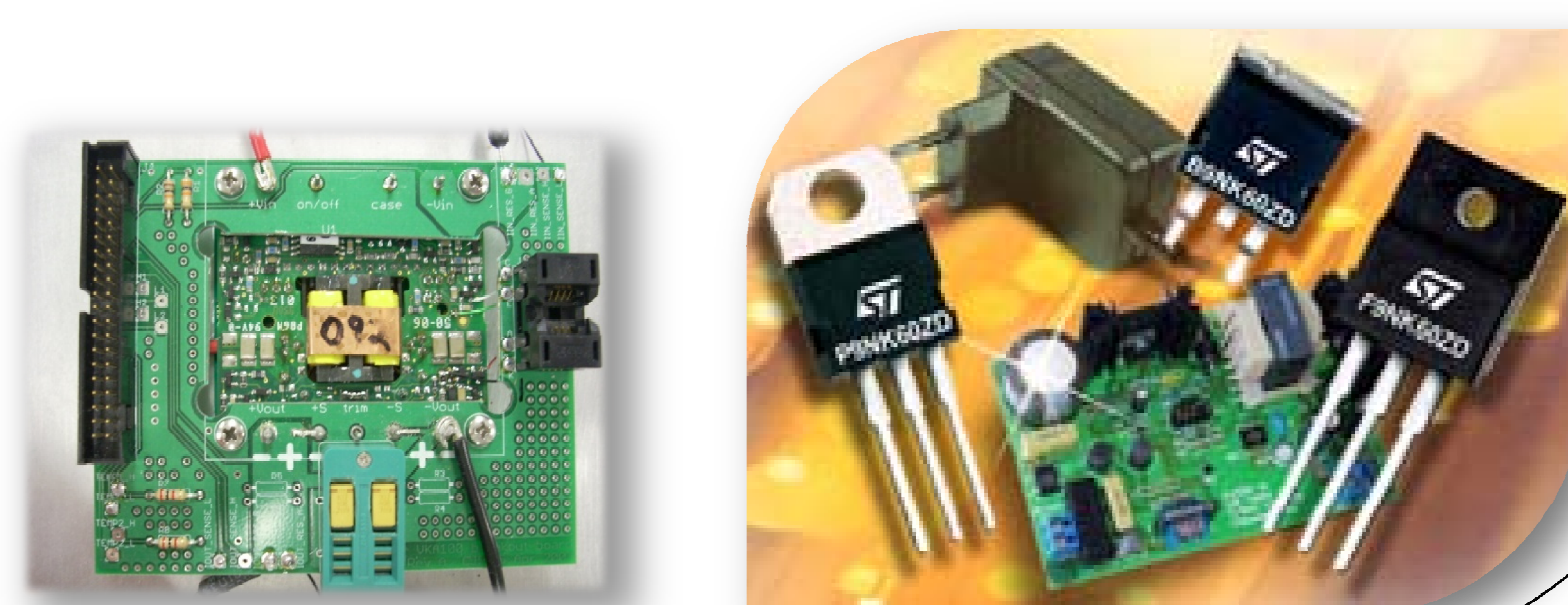
### Motivation

- Electronic components have an increasingly critical role in on-board autonomous functions for vehicle controls, communications, navigation, and radar systems. Future aircraft systems will rely more heavily on electric and electronic components
- To obtain an understanding of the behavior of deteriorated components, as well as the capability to anticipate failures and predict the remaining life of embedded electronics
- Investment in prognostics technologies can enable risk mitigation and increase reliability, while lowering cost for redundant systems



### Objectives

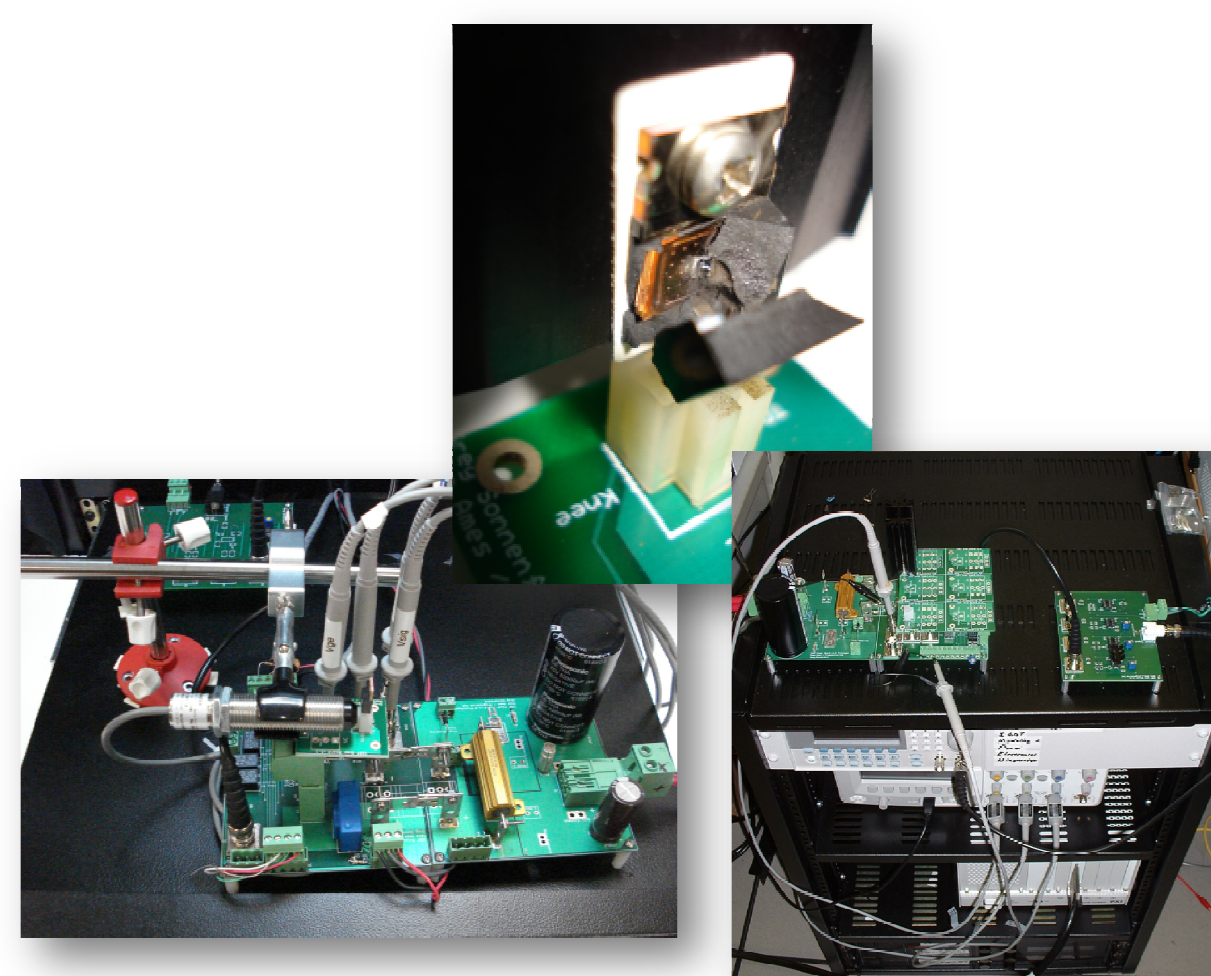
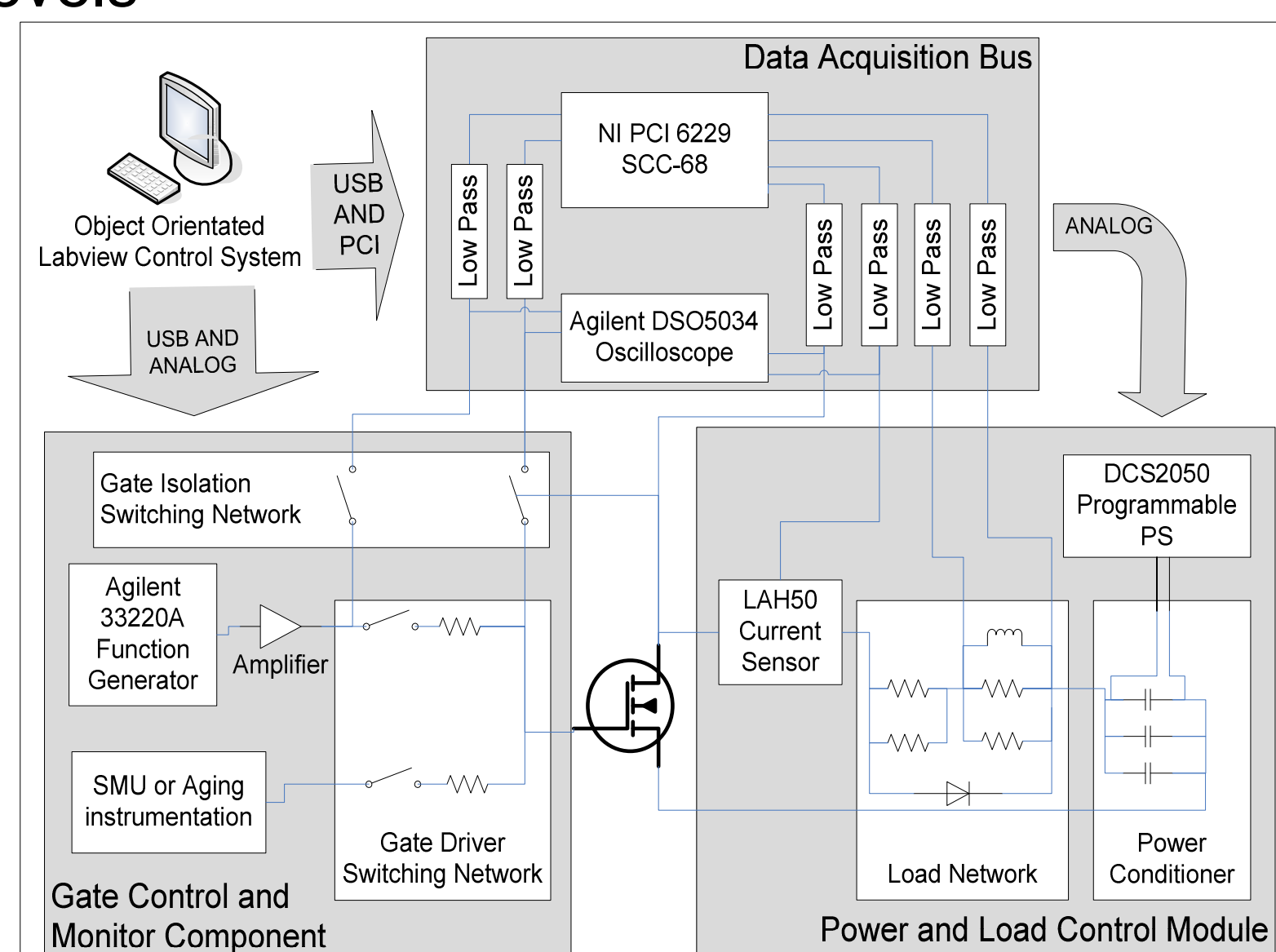
- Identify new and unexplored fault modes and failure mechanisms
- Identify precursors of failures in faulty components
- Discover physics-of-failure models of the degradation process
- Predict the remaining useful life of components and embedded electronics based on physics-of-failure models and identification of precursors of failures



## Methodology

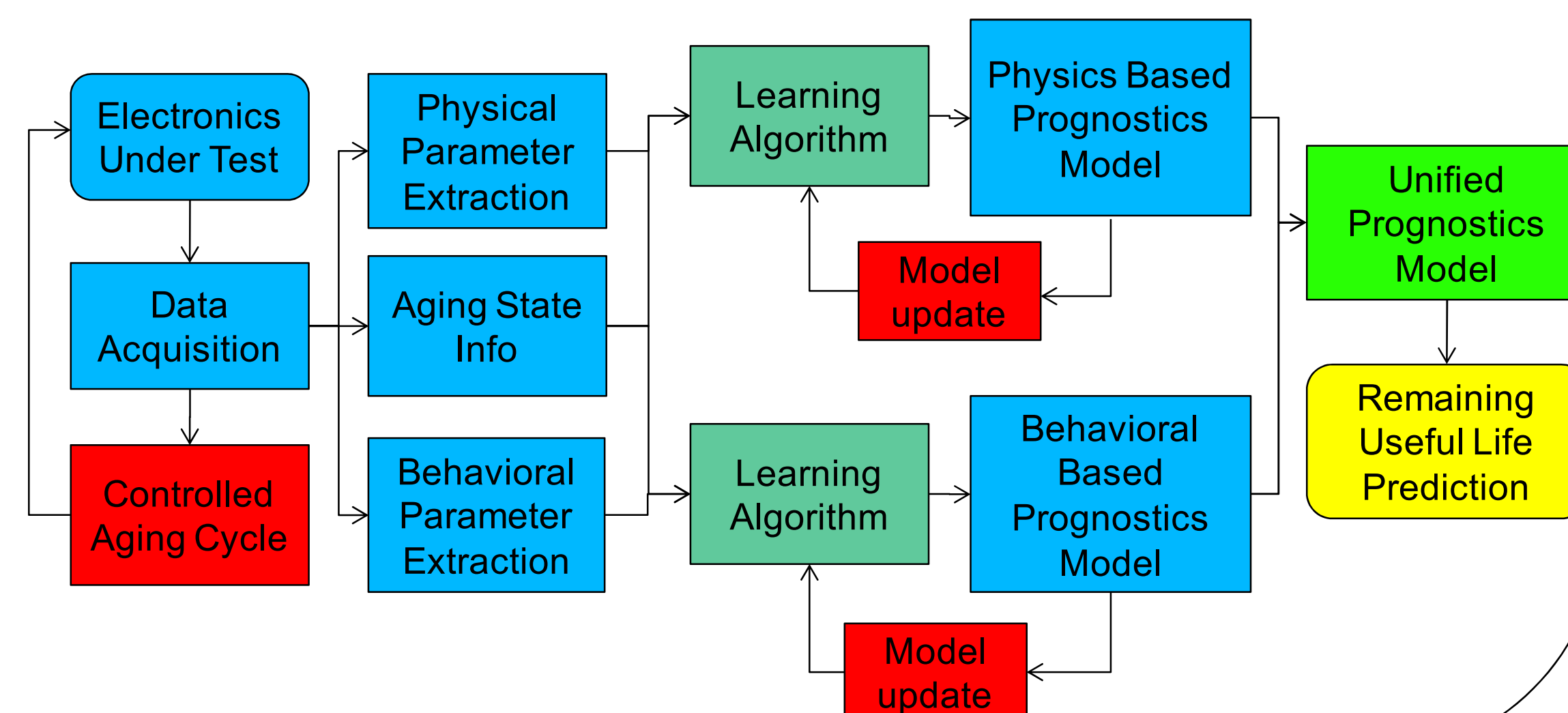
### Aging and Characterization System

- Enables aging and characterization of gate-controlled power transistors
- Supports thermal cycling, dielectric over-voltage, acute/chronic thermal stress, and current overstress
- In-situ state monitoring, including measurements of the steady-state and transient voltages and currents, and thermal transients at varying gate and drain voltage levels



### Remaining Useful Life

- Provide health state indicators in a continuous manner through integration of model and feature-based algorithms
- Update physics-based damage accumulation and aging models based on monitored features
- Estimate health based on anticipated usage profile and execution of the damage propagation model



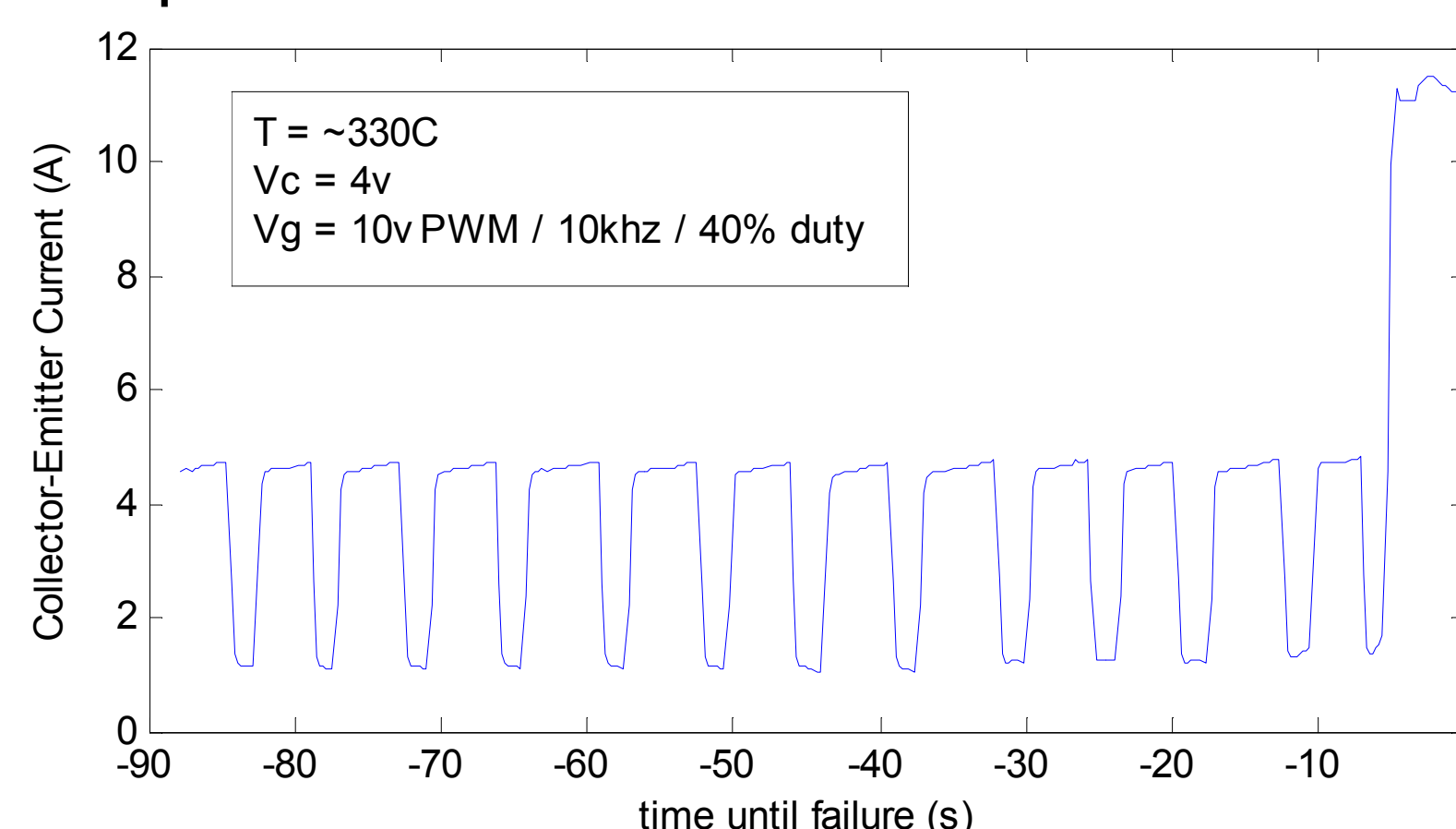
## Results

### IGBT Experiments

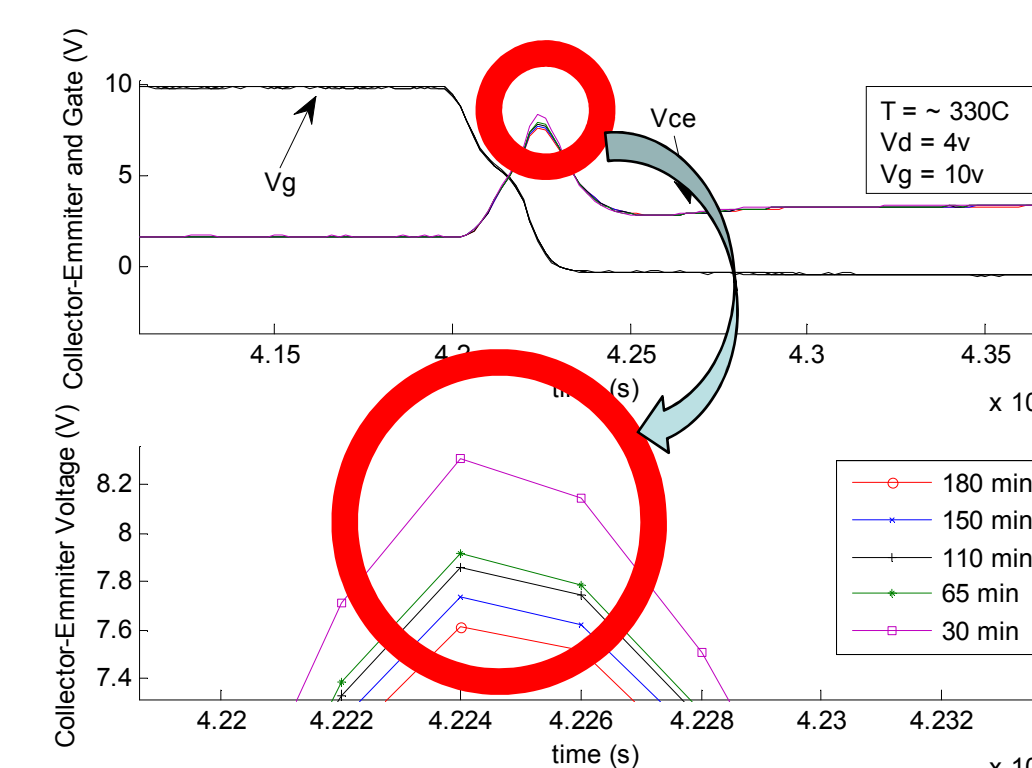
- A preliminary thermal overstress aging test was conducted on IGBTs
- International Rectifier IRG4BC30KD with 600V/15A rating in a T0220 package
- The temperature was measured from the IGBT package without external heat
- The experiment was stopped after thermal runaway or latch-up failure
- A hysteresis temperature controller was used to control the aging process switching the gate voltage
- Aging experiment settings:
  - Serial resistive load of 0.2 Ohms
  - Gate driven by a PWM signal at 10V, 10KHz and 40% duty cycle
  - Power supply at 4V on load circuit
  - Temperature thresholds: Low=329°C, High=330°C, and Runaway= 340°C

### Failures

- The average collector-emitter current was monitor during the during the experiment in order to detect a latch-up condition
- Latch-up failure occurred at ~90 minutes of aging. As a result, gate control was lost. In addition, the device was found to be functional after returning to room temperature



### Precursor of Failure



The collector-emitter voltage turn-OFF transient showed a significant decrease in its peak value with increase in temperature and aging time

